



Title of Change:	Qualification of Maxchip Electronic Corp. (MXP) in Taiwan as an additional wafer fab site for the listed products.
Proposed first ship date:	14 March 2017 <i>or earlier upon customer approval.</i>
Contact information:	Contact your local ON Semiconductor Sales Office or <Osamu Akaki@onsemi.com>
Samples:	Contact your local ON Semiconductor Sales Office
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Yasuhiro.Igarashi@onsemi.com>
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.
Change Part Identification:	Affected products will be identified with date code.
Change category:	<input checked="" type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____
Change Sub-Category(s):	<input checked="" type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____
Sites Affected:	<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input type="checkbox"/> ON Semiconductor site(s) : _____ <input checked="" type="checkbox"/> External Foundry/Subcon site(s) Maxchip Electronics Corp.
Description and Purpose:	<p>This Final Product/Process Change Notification (FPCN) announces the addition of Maxchip Electronics Corp (MXP) as a wafer fabrication site for the list of ON Semiconductor products below. Maxchip Electronics Corp. (MXP) is located in Hsinchu, Taiwan, and is ISO9001 certified.</p> <p>The product design and electrical specifications will not change. A full electrical characterization over the temperature range is performed for each product to check the device functionality and electrical specifications.</p> <p>Qualification tests are designed to show that the reliability of the affected products will continue to meet or exceed ON Semiconductor standards.</p>



Reliability Data Summary:

QV DEVICE NAME: EFC6612R-TF

PACKAGE: CSP-6 / EFCP3517-6DGH-020

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=150°C, 80% max rated VSSS	1008 hrs	0/231
HTGB	JESD22-A108	Ta=150°C, 100% max rated Vgss	1008 hrs	0/231
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/75
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	15000 cyc	0/75
TC	JESD22-A104	Ta= -45°C to +125°C	850 cyc	0/231
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/75
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/75

Electrical Characteristic Summary:

There is no change in the electrical performance. Datasheet specifications remain unchanged.

List of Affected Standard Parts:

Part Number	Qualification Vehicle
EFC6601R-TR	EFC6612R-TR
EFC4621R-TR	